# **1.0A Constant-Current Buck Regulator for Driving High Power LEDs**

The NCL30160 is an NFET hysteretic step-down, constant-current driver for high power LEDs. Ideal for industrial and general lighting applications utilizing minimal external components. The NCL30160 operates with an input voltage range from 6.3 V to 40 V. The hysteretic control gives good power supply rejection and fast response during load transients and PWM dimming to LED arrays of varying number and type. A dedicated PWM input (DIM/EN) enables wide range of pulsed dimming and a high switching frequency up to 1.4 MHz allows the use of smaller external components minimizing space and cost. Protection features include resistor-programmed constant LED current, shorted LED protection, under-voltage and thermal shutdown. The NCL30160 is available in a SOIC-8 package.

### Features

- Integrated 1.0A MOSFET
- VIN Range 6.3 V to 40 V
- Short LED Shutdown Protection
- Up to 1.4 MHz Switching Frequency
- No Control Loop Compensation Required
- Adjustable LED Current
- Single Pin Brightness and Enable/Disable Control Using PWM
- Supports All-Ceramic Output Capacitors and Capacitor-less Outputs
- Thermal Shutdown Protection
- Capable of 100% Duty Cycle Operation
- This is a Pb-Free Device

## **Typical Application**

- LED Driver
- Constant Current Source
- General Illumination
- Industrial Lighting



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SOIC-8 NB **CASE 751** 

## **MARKING DIAGRAM**



А = Assembly Location L

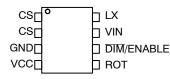
- = Wafer Lot
- = Year

Y

w

- = Work Week
- = Pb-Free Package

## **PIN CONNECTIONS**



### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NCL30160DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

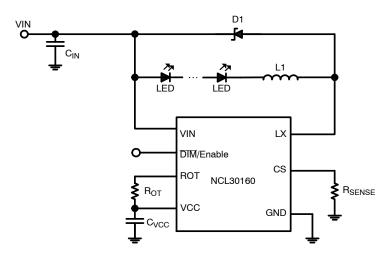


Figure 1. Typical Application Circuit

## PIN FUNCTION DESCRIPTION

Pin	Pin Name	Description	Application Information
1, 2	CS	Current Sense feedback pin	Set the current through the LED array by connecting a resistor from this pin to ground.
3	GND	Ground Pin	Ground. Reference point for all voltages
4	VCC	Output of Internal 5 V linear regulator	The VCC pin supplies the power to the internal circuitry. The VCC is the output of a linear regulator which is powered from VIN. A 2 uF ceramic capacitor is recommended for bypassing and should be placed as close as possible to the VCC and AGND pins. Do not connect to an external load.
5	Rot	Off–Time Setting Resistor	Resistor ROT from this pin to VCC sets the Off–Time range for the hysteretic controller.
6	DIM/EN	PWM Dimming Control & ENABLE	Connect a logic-level PWM signal to this pin to enable/disable the power MOSFET and LED array
7	VIN	Input Voltage Pin	Nominal operating input range is 6.3 V to 40 V. Input supply pin to the internal circuitry and the positive input to the current sense comparators. Due high frequency noise, a 10 $\mu F$ ceramic capacitor is recommended to be placed as close as possible to VIN and power ground.
8	LX	Drain of Internal Power MOSFET	The LX pin connects to the inductor and provides the switching current necessary to operate in hysteretic mode.

## MAXIMUM RATINGS

Rating	Symbol	Min	Max	Unit
VIN to GND	VIN	-0.3	40	V
MOSFET Drain Voltage to GND	LX	-	40	V
VCC to GND	VCC	-	6	V
DIM/EN to GND	DIM	-0.3	6	V
CS to GND	CS	-0.3	6	V
ROT to GND	ROT	-0.3	6	V
Absolute Maximum Junction Temperature	T <sub>J(MAX)</sub>	) 150		°C
Operating Junction Temperature Range	TJ	-40	125	°C
Maximum LED Drive Current	ILIM	1	.5	А
Storage Temperature Range	Temperature Range T <sub>stg</sub> -55 to +125		o +125	°C
Thermal Characteristics SOIC-8 Plastic Package Maximum Power Dissipation @ T <sub>A</sub> = 25°C (Note 1) Thermal Resistance Junction-to-Air (Note 2)	PD R <sub>θJA</sub>	1.11 111.7		W °C/W
Lead Temperature Soldering (10 sec): Re-flow (SMD styles only) Pb-Free (Note 3)	TL	260	peak	°C
Moisture Sensitivity Level (Note 4)	MSL		1	-

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. The maximum package power dissipation limit must not be exceeded.

$$P_{D} = \frac{T_{J(max)} - T_{A}}{R_{\theta JA}}$$

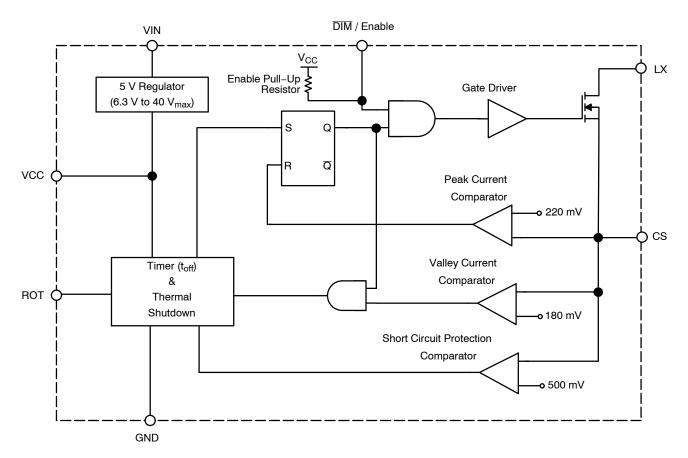
When mounted on a multi-layer board with 35 mm<sup>2</sup> copper area, using 1 oz Cu.
60-180 seconds minimum above 237°C.
Moisture Sensitivity Level (MSL): 1 per IPC/JEDEC standard: J-STD-020A.

**ELECTRICAL CHARACTERISTICS** (Unless otherwise noted:  $V_{IN}$  = 12 V,  $T_A$  = 25°C, unless otherwise specified.)

Symbol	Characteristic	Characteristics			Max	Unit
SYSTEM PARA	AMETERS		•	•	-	
V <sub>IN</sub>	Input Supply Voltage Range	Normal Operation	8.0		40	V
		Functional (Note 5)	6.3			
I <sub>Q_IN</sub>	Quiescent Current i	nto V <sub>IN</sub>		1.5		mA
V <sub>CC</sub>	Internal Regulator Outp	ut (Note 6)		5.0		V
V <sub>UV+</sub>	Under–Voltage Lock–ou (V <sub>IN</sub> Rising)	Under-Voltage Lock-out Threshold		6.0	6.5	V
V <sub>UV-</sub>	Under-Voltage Lock-ou (V <sub>IN</sub> Falling)	Under-Voltage Lock-out Threshold			6.3	V
URRENT LIM	IT AND REGULATION		•			
V <sub>CS_UL</sub>	CS Regulation Upper Limit	25°C	213	220	226	mV
	(CS Increasing, FET Turns-OFF)	–40 to 125°C	209	1	231	1
V <sub>CS_LL</sub>	CS Regulation Lower Limit (CS Decreasing, FET Turns-ON)	25°C	174	180	186	mV
		–40 to 125°C	171		189	
V <sub>OCP</sub>	Over Current Protect Limit (Reference to CS Pin)			500		mV
F <sub>SW</sub>	Switching Frequency Ra			1400	kHz	
			•			
V <sub>PWMH/L</sub>	PWM (DIM/EN) high level input voltage		1.4			V
V <sub>PWML</sub>	PWM (DIM/EN) low level	PWM (DIM/EN) low level input voltage			0.4	V
I <sub>DIM-PU</sub>	DIM/EN Pull-up C	urrent		50		μA
f <sub>pwm</sub>	PWM (DIM/EN) dimming free	equency range	0.1		20	kHz
dmax	Maximum Duty Cycle	(Note 7)		100		%
OWER MOSF	ET		•	•		
V <sub>BRDSS</sub>	Drain-to-Source Breakd	own Voltage	40			V
I <sub>DSS</sub>	Drain-to-Source Leakage Current (V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 40 V)				10	μΑ
R <sub>DS(on)</sub>	On Resistance (Id = 500 mA)				55	mΩ
V <sub>SD</sub>	Source-Drain Body Diode (Forward On-Voltage)			0.8	1.1	V
t <sub>PD_Off</sub>	Propagation Delay V <sub>CS_UL</sub> – LX_High			35	1	ns
HERMAL SHU	JTDOWN			-	-	-
T <sub>SD</sub>	Thermal Shutdo	Thermal Shutdown		165		°C
T <sub>Hyst</sub>	Thermal Hystere		40		°C	
OFF TIMER					-	

t <sub>OFF-MIN</sub>	Minimum Off-time		137	ns

The functional range of V<sub>IN</sub> is the voltage range over which the device will function. Output current and internal parameters may deviate from normal values for V<sub>IN</sub> and V<sub>CC</sub> voltages between 6.3 V and 8 V, depending on load conditions
V<sub>CC</sub> should not be driven from a voltage higher than V<sub>IN</sub> or in the absence of a voltage at V<sub>IN</sub>.
Guaranteed by design.





TYPICAL APPLICATION CIRCUITS AND WAVEFORMS

(T<sub>J</sub> = 25°C, Unless Otherwise Specified)

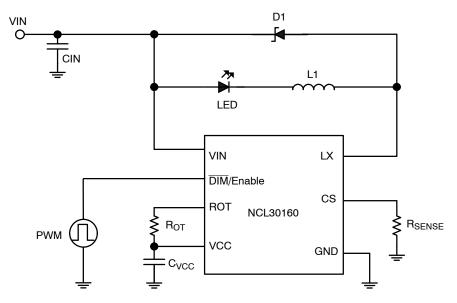


Figure 3. Typical Application Circuit To Drive One LED (Buck)

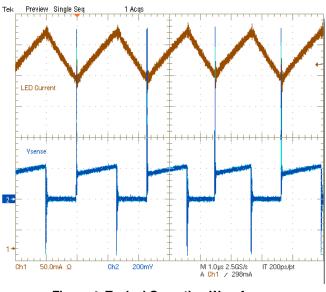


Figure 4. Typical Operation Waveforms (V<sub>CC</sub> = 12 V, V<sub>LED</sub> = 6.5 V, R<sub>SENSE</sub> = 0.68  $\Omega$ , L = 100  $\mu$ H)

# THEORY OF OPERATION

This switching power supply is comprised of an inverted buck regulator controlled by a current mode, hysteretic control circuit. The buck regulator operates exactly like a conventional buck regulator except the power device placement has been inverted to allow for a low side power FET. Referring to Figure 1, when the FET is conducting, current flows from the input,through the inductor, the LED and the FET to ground.

When the FET shuts off, current continues to flow through the inductor and LED, but is diverted through the diode (D1). This operation keeps the current in the LED continuous with a continuous current ramp.

The control circuit controls the current hysteretically. Figure 2 illustrates the operation of this circuit. The CS comparator thresholds are set to provide a 10% current ripple. The peak current comparator threshold of 220 mV sets  $I_{peak}$  at 10% above the average current while the valley current comparator threshold of 180 mV sets  $I_{valley}$  at 10% below the average current.

When the FET is conducting, the current in the inductor ramps up. This current is sensed by an external sense resistor that is connected from CS to ground. When the CS pin reaches 220 mV, the peak current comparator turns off the power FET. A conventional hysteretic controller would monitor the load current and turn the switch back on when the CS pin reaches 180 mV. But in this topology, the current information is not available to the control circuit when the FET is off. To set the proper FET off time, the CS voltage is sensed when the FET is turned back on and a correction signal is sent to the off time circuit to adjust the off time as necessary.

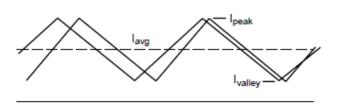
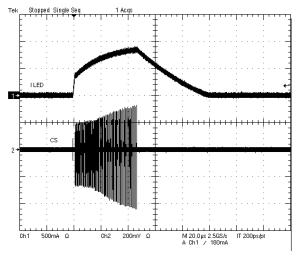


Figure 5. Typical Current Waveforms

The current waveshape is triangular, and the peak and valley currents are controlled. The average value for a triangular waveshape is halfway between the peak and valley, so even with changes in duty cycle due to input voltage variations or load changes, the average current will remain constant.

In the event there is a short-circuit across the LEDs, a large amount of current could potentially flow through the circuit during startup. To protect against this, the NCL30160 comes with a short circuit protection feature. If the voltage on the CS pin is detected to be greater than 500 mV (equating to 2.5 times the intended average output current), the NCL31060 will turn off the FET, and prevent the FET from turning on again until power is recycled to NCL30160.



**Figure 6. Short-Circuit Protection** 

When  $V_{IN}$  rises above the UVLO threshold voltage, switching operation of the FET will begin. However, until the  $V_{IN}$  voltage reaches 8 V, the VCC regulator may not provide the expected gate drive voltage to the FET. This could result in the  $R_{DS(on)}$  of the FET being higher than expected or there not being enough gate drive capability to operate at the maximum rated switching frequency. For optimal performance, it is recommended to operate the part at a V<sub>IN</sub> voltage of 8 V or greater.

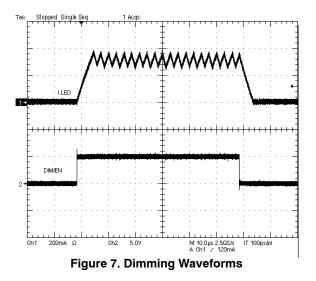
#### **Setting The Output Current**

The average output current is determined as being the middle of the peak and valley of the output current, set by the CS comparator thresholds. The nominal average output current will be the current value equivalent to 200 mV at the CS pin. The proper  $R_{SENSE}$  value for a desired average output current can be calculated by:

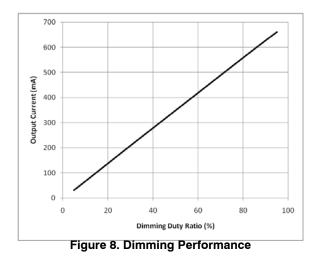
$$\mathsf{R}_{\mathsf{SENSE}} = \frac{200 \text{ mV}}{\mathsf{I}_{\mathsf{LED}}}$$

#### **PWM Dimming**

For a given R<sub>SENSE</sub> value, the average output current, and therefore the brightness of the LED, can be set to a lower value through the DIM/EN pin. When the DIM/EN pin is brought low, the internal FET will turn off and switching will remain off until the DIM/EN pin is brought back into its high state.



By applying a pulsed signal to DIM/EN, the average output current can be adjusted to the duty ratio of the pulsed signal. It is recommended to keep the frequency of the DIM/EN signal above 100 Hz to avoid any visible flickering of the LED.



#### Inductor Selection

The inductor that is used directly affects the switching frequency the driver operates at. The value of the inductor sets the slope at which the output current rises and falls during the switching operation. The slope of the current, in turn, determines how long it takes the current to go from the valley point of the current ripple to the peak when the FET is on and the current and rising, and how long it takes the current to go from the peak point of the current to the valley when the FET is off and the current is falling. These times can be approximated from the following equations:

$${}^{t}_{ON} = \frac{L \times \Delta I}{VIN - V_{LED} - I_{OUT} \times \left(FET_{R_{DS}}(on) + DCR_{L} + R_{SENSE}\right)}$$

$$t_{\mathsf{OFF}} = \frac{\mathsf{L} \times \Delta \mathsf{I}}{\mathsf{V}_{\mathsf{LED}} + \mathsf{V}_{\mathsf{diode}} + \mathsf{I}_{\mathsf{OUT}} \times \mathsf{DCR}_{\mathsf{L}}}$$

Where DCR<sub>L</sub> is the dc resistance of the inductor,  $V_{LED}$  is the forward voltages of the LEDs,  $FET_{RDS(ON)}$  is the on-resistance of the power MOSFET, and  $V_{diode}$  is the forward voltage of the catch diode.

The switching frequency can then be approximated from the following:

$$f_{SW} = \frac{1}{t_{ON} + t_{OFF}}$$

Higher values of inductance lead to slower rates of rise and fall of the output current. This allows for smaller discrepancies between the expected and actual output current ripple due to propagation delays between sensing at the CS pin and the turning on and off of the power MOSFET. However, the inductor value should be chosen such that the peak output current value does not exceed the rated saturation current of the inductor.

#### **Catch Diode Selection**

The catch diode needs to be selected such that average current through the diode does not exceed the rated average forward current of the diode. The average current through the diode can be calculated as:

$$I_{avg\_diode} = I_{OUT} \times \frac{t_{OFF}}{t_{ON} + t_{OFF}}$$

It is also important to select a diode that is capable of withstanding the peak reverse voltage it will see in the application. It is recommended to select a diode with a rated reverse voltage greater than VIN. It is also recommended to use a low-capacitance Schottky diode for better efficiency performance.

#### Selecting The Off-Time Setting Resistor

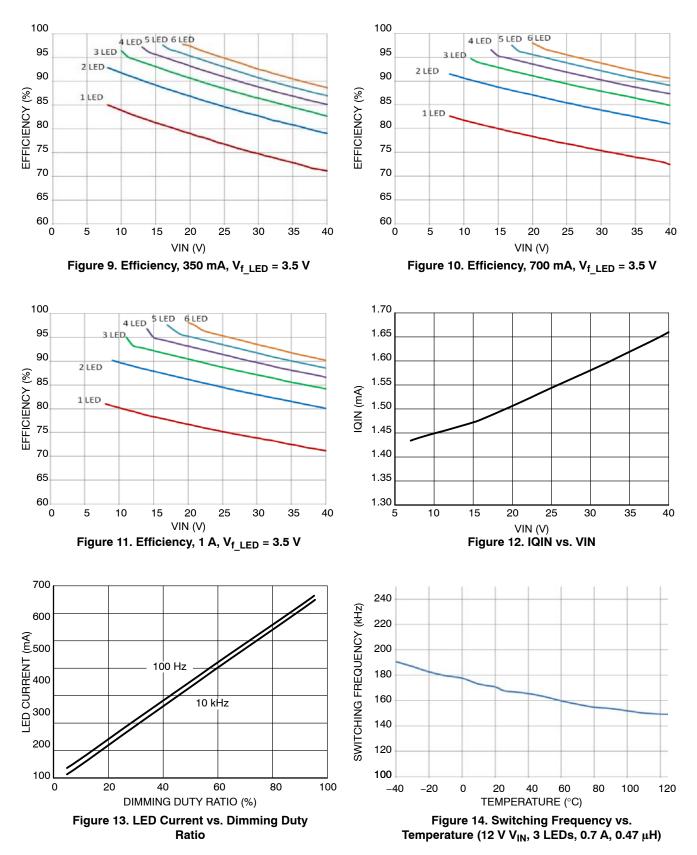
The off-time setting resistor  $(R_{OT})$  programs the NCL30160 with the initial time duration that the MOSFET is turned off when the switching operation begins. During subsequent switching cycles, the voltage at the CS pin is sensed every time the MOSFET is turned on, and the off-time will be adjusted depending on how much of a discrepancy exists between the sensed value and the CS lower limit threshold value. The R<sub>OT</sub> value can be calculated using the following equation:

$$R_{OT} = t_{OFF} \times 10^{11} \, \Omega$$

Where  $t_{OFF}$  is the expected off time during normal switching operation, calculated in the Inductor Selection section above.

#### **Input Capacitor**

A decoupling capacitor from VIN to ground should be used to provide the current needed when the power MOSFET turns on. A 4.7  $\mu$ F ceramic capacitor is recommended.







\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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#### SOIC-8 NB CASE 751-07 ISSUE AK

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STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 COLLECTOR, #2 3. 4 COLLECTOR, #2 BASE, #2 5. EMITTER, #2 6. 7 BASE #1 EMITTER, #1 8. STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN SOURCE 4. SOURCE 5. 6. GATE GATE 7. 8. SOURCE STYLE 10: GROUND PIN 1. BIAS 1 OUTPUT 2. З. GROUND 4. 5. GROUND 6 BIAS 2 INPUT 7. 8. GROUND STYLE 14: PIN 1. N-SOURCE 2. N-GATE P-SOURCE 3 P-GATE 4. P-DRAIN 5 6. P-DRAIN N-DRAIN 7. N-DRAIN 8. STYLE 18: PIN 1. ANODE 2. ANODE SOURCE 3. GATE 4. 5. DRAIN 6 DRAIN CATHODE 7. CATHODE 8. STYLE 22 PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3 COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND STYLE 26: PIN 1. GND 2 dv/dt З. ENABLE 4. ILIMIT 5. SOURCE SOURCE 6. SOURCE 7. 8. VCC STYLE 30: DRAIN 1 PIN 1. DRAIN 1 2 GATE 2 З. SOURCE 2 4. SOURCE 1/DRAIN 2 SOURCE 1/DRAIN 2 5. 6.

STYLE 3: PIN 1. DRAIN, DIE #1 DRAIN, #1 2. DRAIN, #2 З. 4. DRAIN, #2 GATE, #2 5. SOURCE, #2 6. 7 GATE #1 8. SOURCE, #1 STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS THIRD STAGE SOURCE GROUND З. 4. 5. DRAIN 6. GATE 3 SECOND STAGE Vd 7. FIRST STAGE Vd 8. STYLE 11: PIN 1. SOURCE 1 GATE 1 SOURCE 2 2. 3. GATE 2 4. 5. DRAIN 2 6. DRAIN 2 DRAIN 1 7. 8. DRAIN 1 STYLE 15: PIN 1. ANODE 1 2. ANODE 1 ANODE 1 3 ANODE 1 4. 5. CATHODE, COMMON CATHODE, COMMON CATHODE, COMMON 6. 7. CATHODE, COMMON 8. STYLE 19: PIN 1. SOURCE 1 GATE 1 SOURCE 2 2. 3. GATE 2 4. 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. **MIRROR 1** STYLE 23: PIN 1. LINE 1 IN COMMON ANODE/GND COMMON ANODE/GND 2. 3 LINE 2 IN 4. LINE 2 OUT 5. COMMON ANODE/GND COMMON ANODE/GND 6. 7. LINE 1 OUT 8. STYLE 27: PIN 1. ILIMIT 2 OVI 0 UVLO З. 4. INPUT+ 5. SOURCE SOURCE 6. SOURCE 7. 8 DRAIN

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STYLE 4: PIN 1. 2. ANODE ANODE ANODE З. 4. ANODE ANODE 5. 6. ANODE 7 ANODE COMMON CATHODE 8. STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 BASE, #2 З. COLLECTOR, #2 4. COLLECTOR, #2 5. 6. EMITTER, #2 EMITTER, #1 7. 8. COLLECTOR, #1 STYLE 12: PIN 1. SOURCE SOURCE 2. 3. GATE 4. 5. DRAIN 6. DRAIN DRAIN 7. 8. DRAIN STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 EMITTER, DIE #2 3 BASE, DIE #2 4. 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 COLLECTOR, DIE #1 7. COLLECTOR, DIE #1 8. STYLE 20: PIN 1. SOURCE (N) GATE (N) SOURCE (P) 2. 3. 4. GATE (P) 5. DRAIN 6. DRAIN DRAIN 7. 8. DRAIN STYLE 24: PIN 1. BASE 2. EMITTER 3 COLLECTOR/ANODE COLLECTOR/ANODE 4. 5. CATHODE 6. CATHODE COLLECTOR/ANODE 7. 8. COLLECTOR/ANODE STYLE 28: PIN 1. SW\_TO\_GND 2. DASIC OFF DASIC\_SW\_DET З. 4. GND 5. 6. V MON VBULK 7. VBULK 8 VIN

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SOURCE 1/DRAIN 2

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